



Material Content Data Sheet



Sales Product Name		TLE9255WLC		Issued		22. July 2019		
MA#		MA005351834						
Package		PG-TSON-14-3		Weight*		42.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.199	2.85	2.85	28523	28523
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		119	
	non noble metal	zinc	7440-66-6	0.020	0.05		476	
	non noble metal	iron	7439-89-6	0.401	0.95		9525	
wire	non noble metal	copper	7440-50-8	16.263	38.67	39.68	386745	396865
	non noble metal	copper	7440-50-8	0.091	0.22	0.22	2155	2155
	encapsulation	organic material	carbon black	1333-86-4	0.046	0.11		1085
encapsulation	plastics	epoxy resin	-	2.350	5.59		55893	
	inorganic material	silicondioxide	60676-86-0	20.423	48.56	54.26	485672	542650
leadfinish	non noble metal	tin	7440-31-5	0.621	1.48	1.48	14773	14773
plating	noble metal	silver	7440-22-4	0.091	0.22	0.22	2157	2157
glue	plastics	epoxy resin	-	0.135	0.32		3219	
	noble metal	silver	7440-22-4	0.406	0.97	1.29	9658	12877
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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